

Title (en)

Process for reducing the solubility of copper at the inner surface of a copper pipe

Title (de)

Verfahren zur Verringerung der Kupferlöslichkeit an der inneren Oberfläche eines Kupferrohrs

Title (fr)

Procédé de réduction de la solubilité de cuivre à la surface intérieure d'un tuyau en cuivre

Publication

EP 1347078 A3 20040211 (DE)

Application

EP 03005781 A 20030314

Priority

DE 10213185 A 20020323

Abstract (en)

[origin: EP1347078A2] Inner surface of a copper pipe is sealed by a layer of tin coating, to prevent copper ions dispersing into drinking water flowing through it. The process parameters of the tin coating are set to give a consistent tin crystal growth during degreasing and pickling, adjusting the flow speed to at most 1 m/second, at a temperature of 50-80 degreesC in a working time of 1-10 minutes. The plane of the tin crystals is parallel to the plane of the copper crystals, and their directions are at right angles to each other.

IPC 1-7

C23C 18/31

IPC 8 full level

C23C 30/00 (2006.01); **C23C 18/31** (2006.01)

CPC (source: EP US)

C23C 18/31 (2013.01 - EP US)

Citation (search report)

- [A] EP 0848084 A1 19980617 - SUMITOMO LIGHT METAL IND [JP]
- [A] EP 0915183 A1 19990512 - ATOTECH DEUTSCHLAND GMBH [DE], et al
- [A] PATENT ABSTRACTS OF JAPAN vol. 1999, no. 03 31 March 1999 (1999-03-31)

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DOCDB simple family (application)

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